

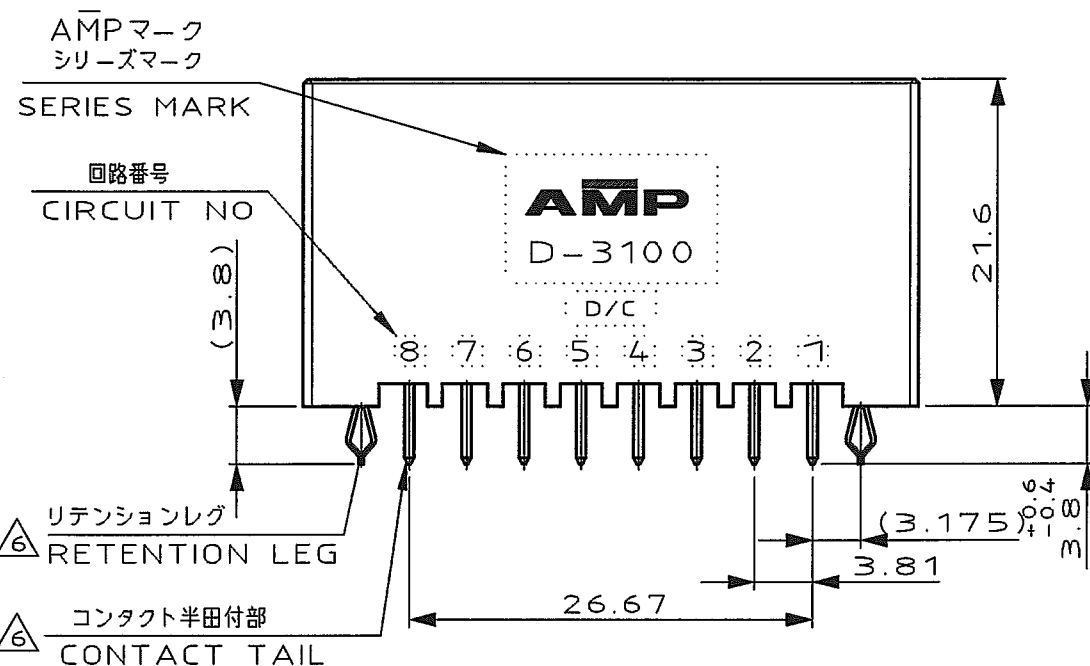
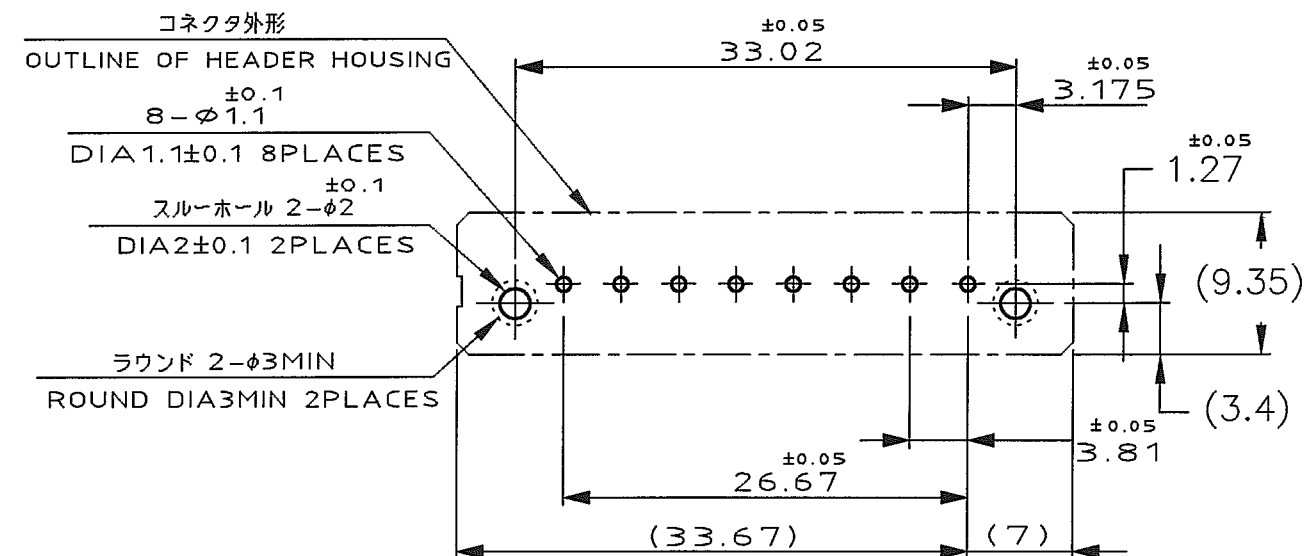
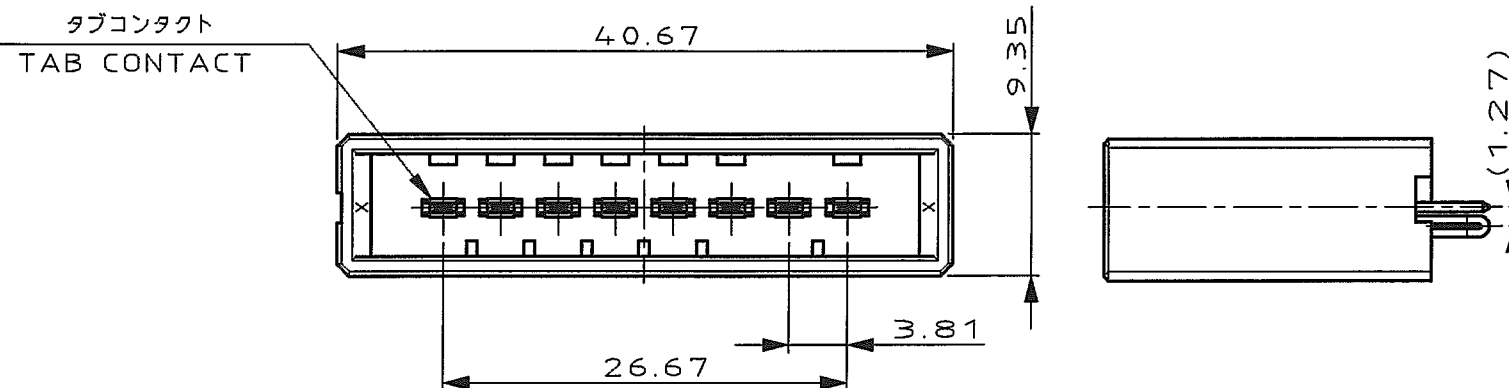
NUMBER 178317



METRIC

DIMENSIONS IN MILLIMETERS, DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/783

推奨基板取付け寸法

PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): $0.38 \mu\text{m}$ MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): $0.76 \mu\text{m}$ MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): $2.0 \mu\text{m}$ MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: $0.38 \mu\text{m}$ MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: $0.76 \mu\text{m}$ MIN金めっき
- めっき: コンタクト: 全面Ni下地
接触部: $2.0 \mu\text{m}$ MINスズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	1-178317-5
△6	△3	1-178317-3
△6	△2	1-178317-2
(FINISH)		製品番号 (PART NO.)

E	REVISED	FJD0-0039-03	TS	S.M.	6/2 '03
D	REVISED	FJD0-0114-03	TS	S.M.	25. APR '03
C	REVISED	FJ00-2744-95	KI	Y.I.	16/ JUN '95
B	REVISED	FJ00-0838-94	NM	S.M.	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M.	4/20 '94
LTR	REVISION RECORD		DR	CHK	DATE

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WIRE RANGE		INSULATION DIA		NAME	
mm?(AWG -)		mmφ		8 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 19 APR 94 N. Matsubara		DE. 19 APR 94 N. Matsubara		SIZE LOC NUMBER	
CHK. 20 APR 94 S. MANABE		APP. 20 APR 94 S. MANABE		10mm ±0.3 10mm 30mm ±0.4 30mm 100mm ±0.45 角 度 ±3°	
				SCALE REV. SHEET	
				2-1 E 1 OF 1	

(CUSTOMER DRAWING) 顧客用図面